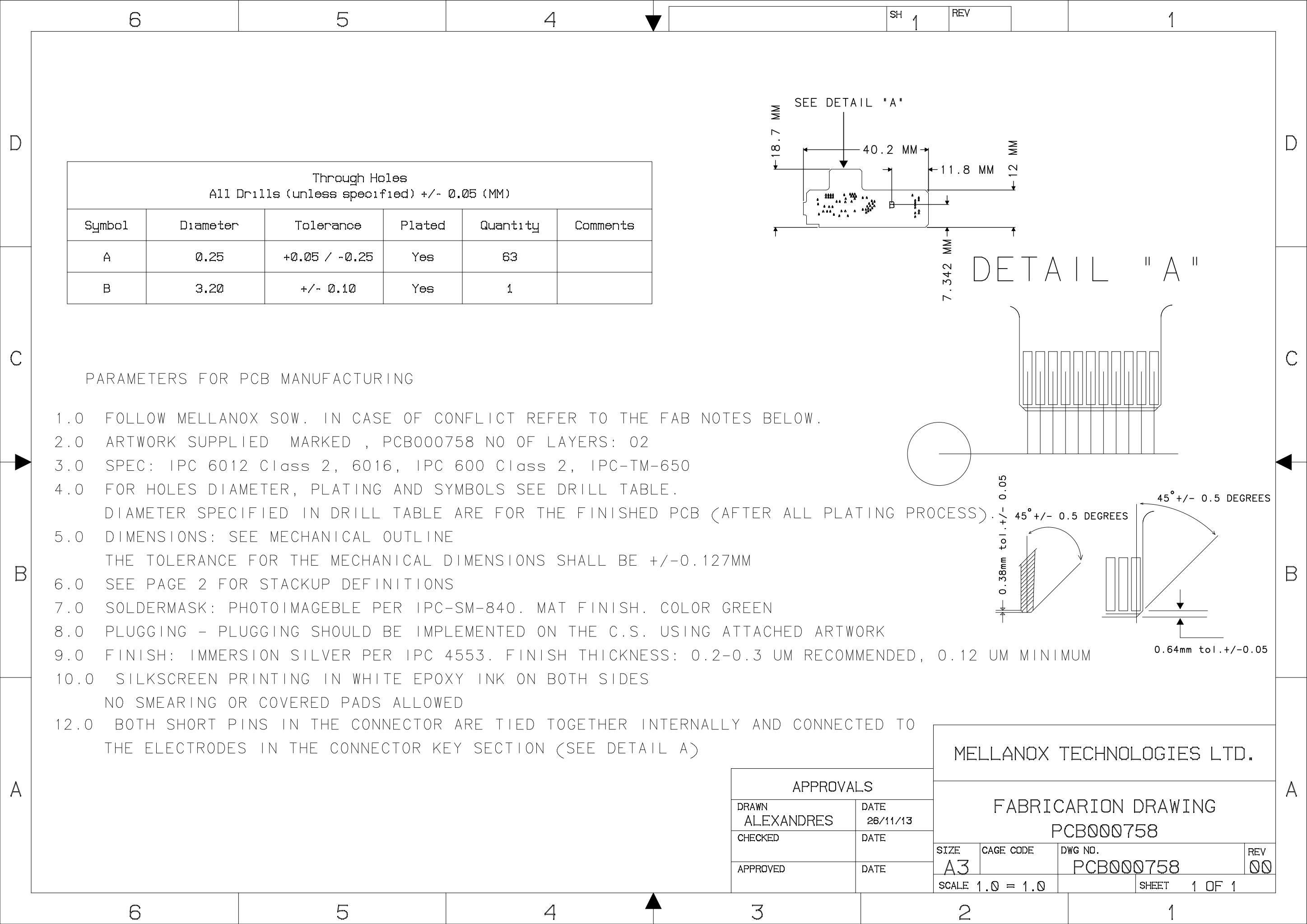




6

5

4

3

2

1

Mellanox Technologies, Ltd.
Beit Mellanox
Yokneam POB 586,
Israel 20692
Telephone: +972-4-909-7200
Fax: +972-4-959-3245

Date:	12/1/2013
P/N:	PCB000758
Layers:	2
Total Thickness:	1.57mm±0.15mm
Finish:	Immersion silver

Stack-up and impedance requirements

Material:	FR4-High TG
PCB size and PCB units per array	40.2mm X 18.7mm; 12 units
PCB Utilization (%)	
Gold finger:	yes
Back drill depth/width types on CS:	0
Back drill depth/width types on PS:	0



All dimensions are in mils unless otherwise stated

Layer	Copper parameters				Resin parameters				Impedance parameters								
	signal/ Power/ GND	Copper weight [oz]	Copper thickness after plaiting [Mil]	Copper roughness	Dielectric thickness	Material	Glass type	Resin content [%]	Differential pairs parameters					SE signal parameters			
									Imp. [Ω]	Default		Neck-down		Imp.[Ω]	Default Width	CoPlaner Space	Neck-down Width
										Width	Space	Width	Space				
Layer 1 - CS	Signal	1 oz	2.7						NA	NA	NA	NA	NA	NA	NA	NA	
Core					56	FR4-HIGH TG	EM827 CORE 56MIL										
Layer 2 - PS	Signal	1 oz	2.7						same as layer 1					NA	NA	NA	
If you have any queries please do not hesitate to contact: Igor Gurevich, HW engineer, Cell: +972 (50) 7948629 igorg@mellanox.com									Revision control:								
									Revision		Date		Description				
									00		12/1/2013		Final release				

Notes:	
1	Impedance controlled differential pairs widths are defined with two digits after the decimal points inside the gerbers. Eg 9 mil width is defined as 8.99.
2	The dialectric thickness, line widths and differential space values are nominal values. Minor changes can be done to meet the impedance requirements.(HW designer approval is a must)